

SOT1989-1

LFBGA269, low-profile fine-pitch ball grid array package, 269 terminals, 0.8 mm pitch, 14 mm x 14 mm x 1.37 mm body

19 July 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA269
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	06-07-2018
Manufacturer package code	98ASA01284D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	14	-	mm
package width	-	14	-	mm
seated height	-	1.37	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	269	-	



2 Package outline

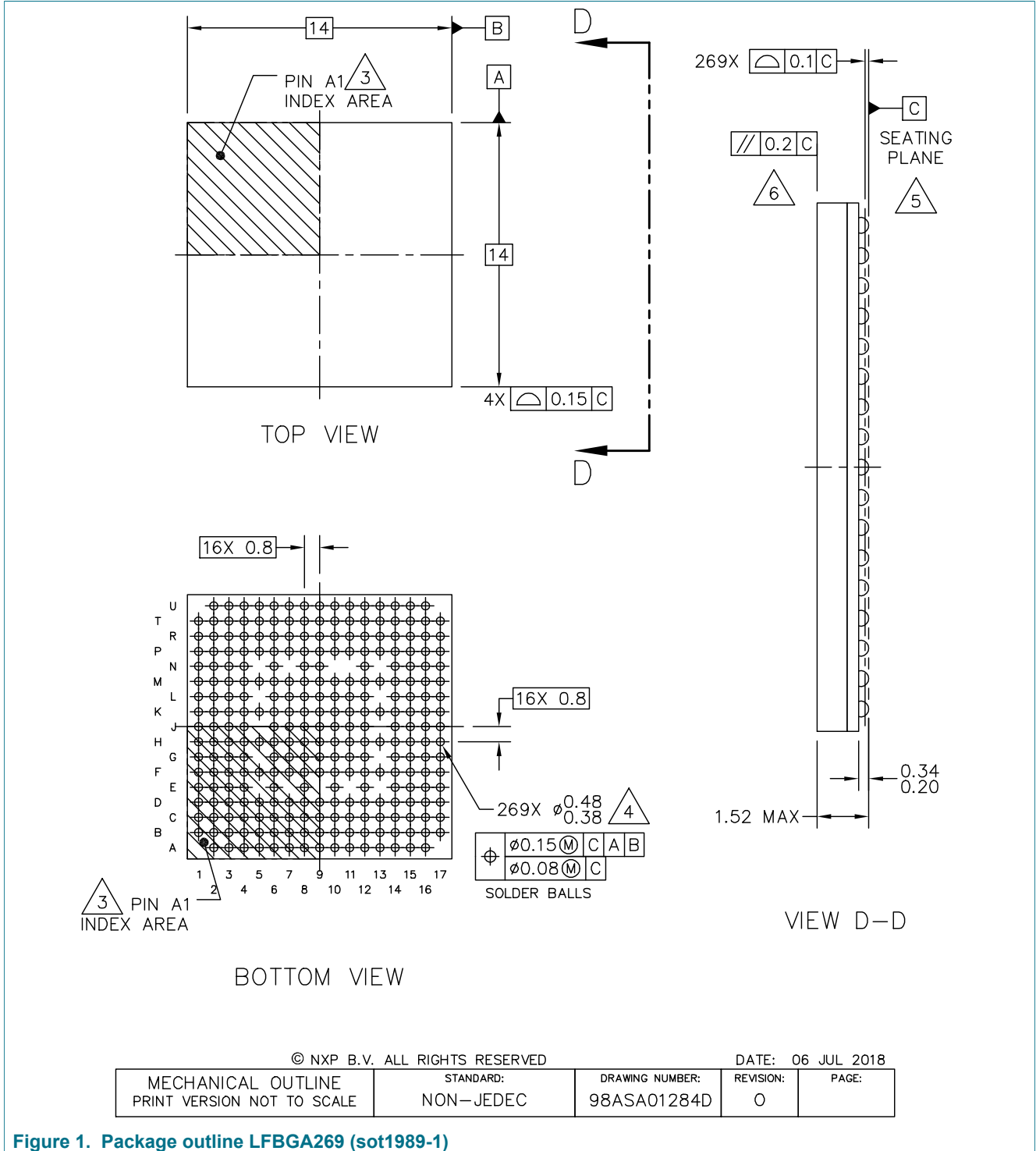


Figure 1. Package outline LFBGA269 (sot1989-1)

LFBGA269, low-profile fine-pitch ball grid array package, 269 terminals, 0.8 mm pitch, 14 mm x 14 mm x 1.37 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 2. Package outline note LFBGA269 (sot1989-1)

3 Soldering

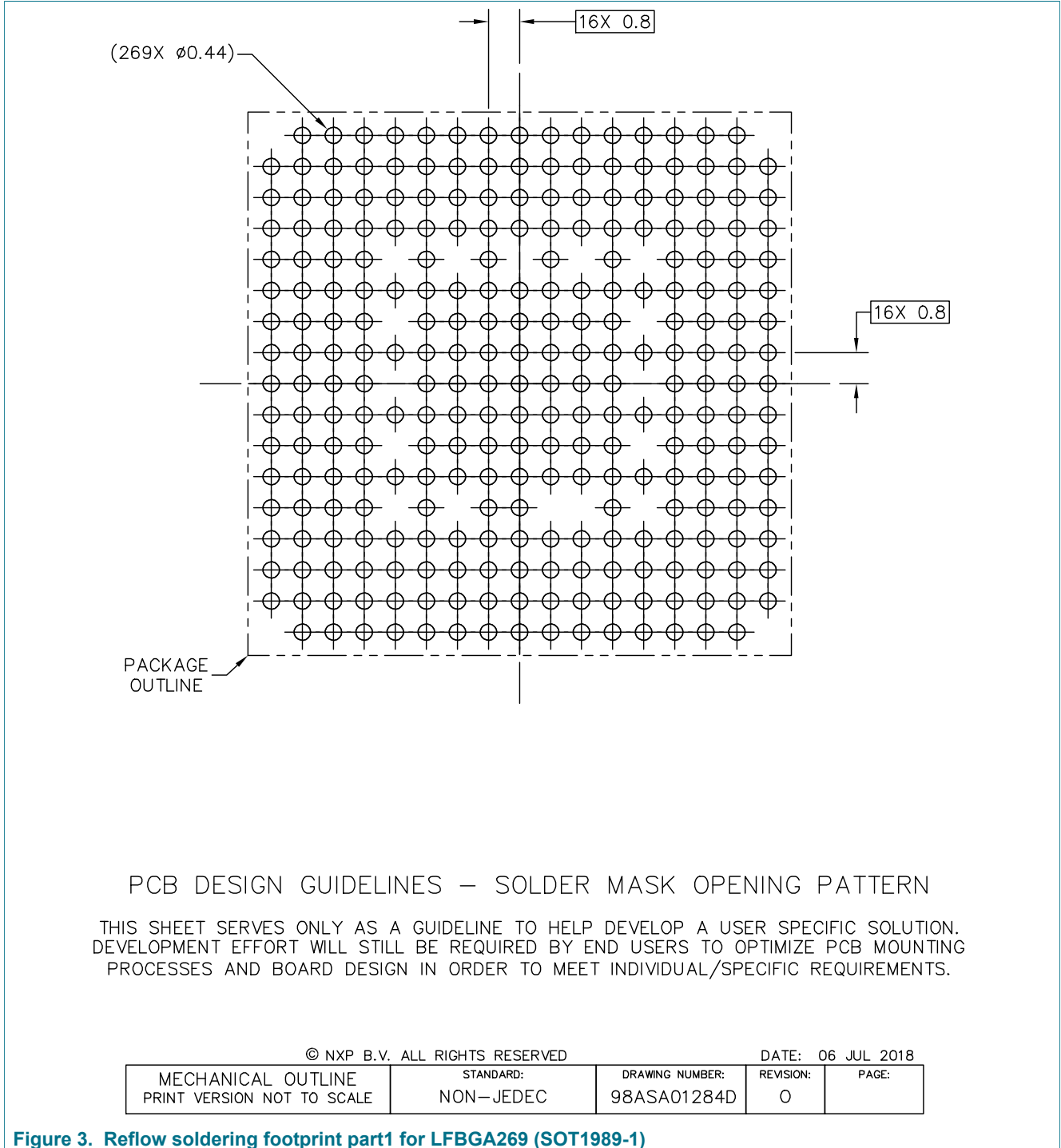
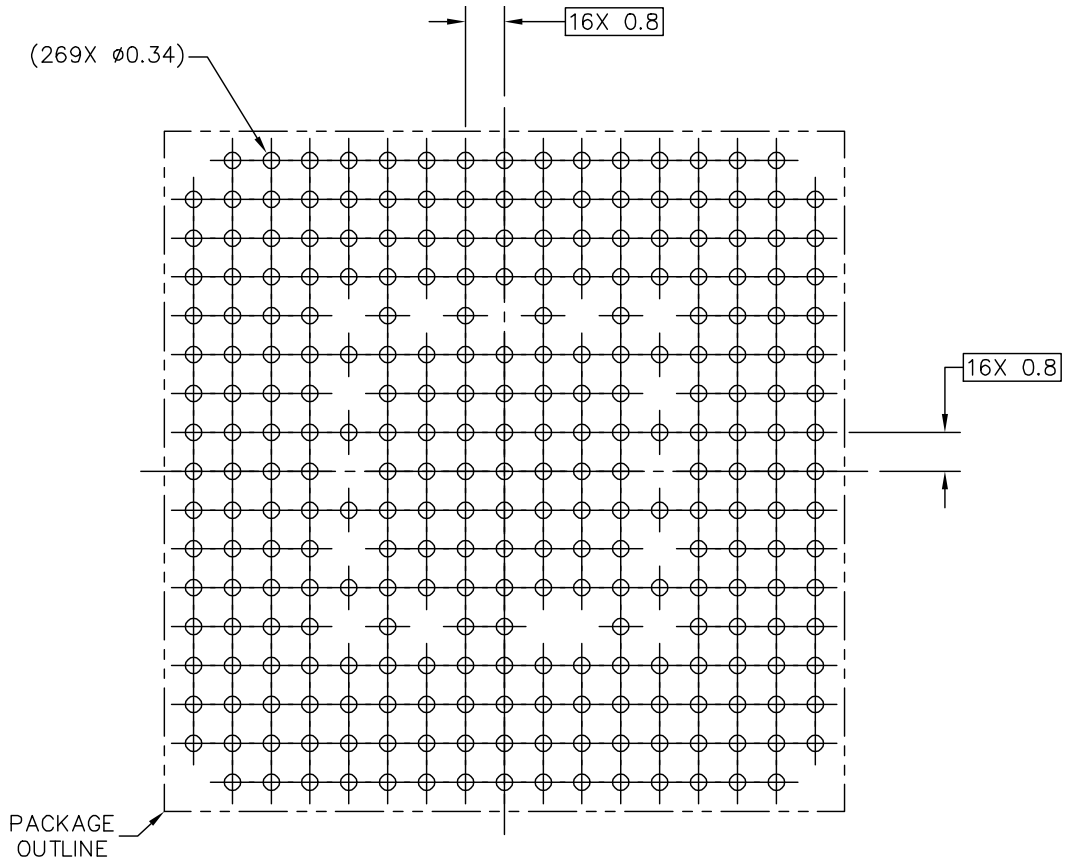


Figure 3. Reflow soldering footprint part1 for LFBGA269 (SOT1989-1)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

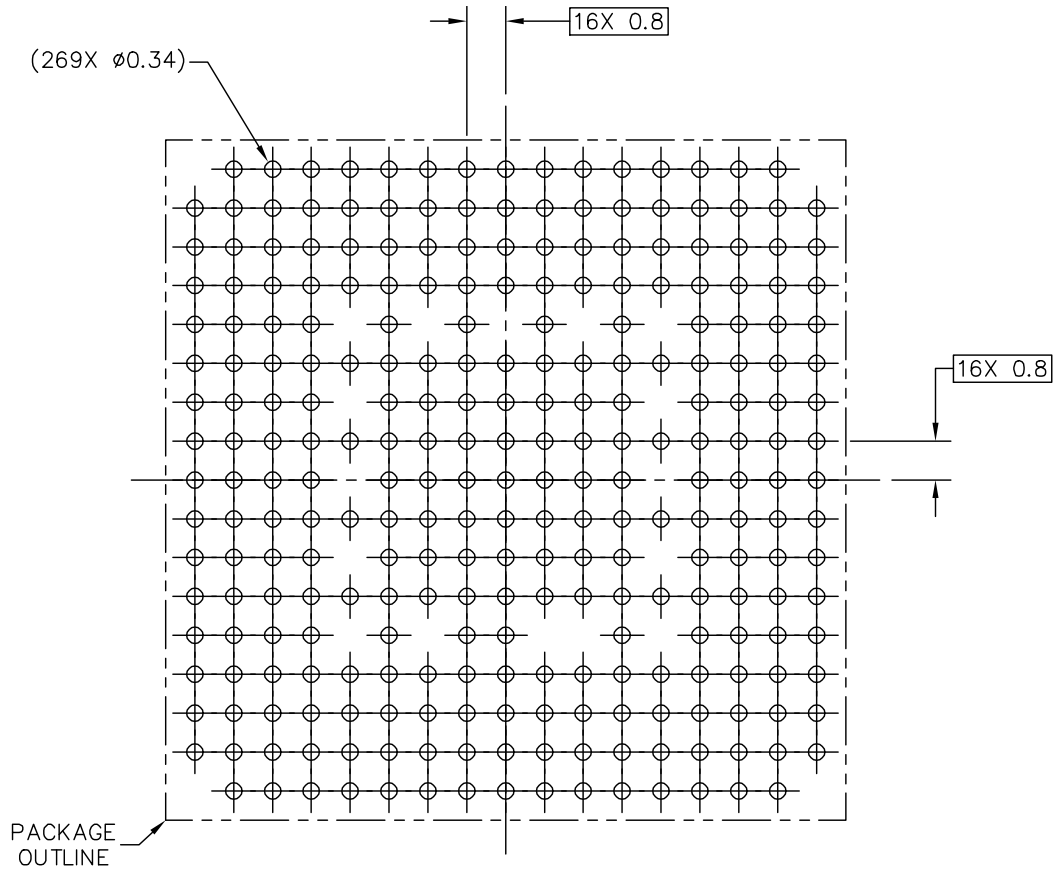
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Figure 4. Reflow soldering footprint part2 for LFBGA269 (SOT1989-1)

LFBGA269, low-profile fine-pitch ball grid array package, 269 terminals, 0.8 mm pitch, 14 mm x 14 mm x 1.37 mm body



RECOMMENDED STENCIL THICKNESS 0.125
 PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for LFBGA269 (SOT1989-1)

4 Legal information

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